



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC360N15NS3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000844168						
<b>Package</b>		PG-TDSON-8-1		<b>Weight*</b>		119.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.357	1.97	1.97	19669	19669
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		316	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.50	31.54	315140	315551
wire	non noble metal	copper	7440-50-8	0.073	0.06	0.06	606	606
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		702	
	plastics	epoxy resin	-	5.973	4.99		49850	
	inorganic material	silicondioxide	60676-86-0	36.007	30.05	35.11	300502	351054
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12115	12115
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1381	1381
solder	noble metal	silver	7440-22-4	0.056	0.05		469	
	non noble metal	tin	7440-31-5	0.045	0.04		375	
	non noble metal	lead	7439-92-1	2.146	1.79	1.88	17908	18752
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.45	9.46	94472	94595
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		186	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.60	18.63	186035	186277
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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